



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: K. AOTA, et al.  
Application No.: 10/600,577  
Filed: June 23, 2003  
For: FRICTION STIR WELDING METHOD AND STRUCTURE BODY FORMED  
Group Art Unit: 1725  
Examiner: K. S. Stoner  
Confirm. No.: 9631

**TERMINAL DISCLAIMER****Mail Stop: AMENDMENT - FEE**

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

June 29, 2005

Sir:

Petitioner, Hitachi, Ltd., having its place of business at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo 100, Japan, represents that it is the sole owner of the entire interest of U.S. Application No. 10/600,577, filed June 23, 2003, for FRICTION STIR WELDING METHOD AND STRUCTURE BODY FORMED, and that a copy of the Assignment of all rights in connection therewith is enclosed herewith.

Petitioner hereby disclaims all that portion of the term of any patent to be issued on the above-identified application subsequent to the expiration date of the full statutory term, defined in 35 USC 154 to 156 and 173, of U.S. Patent No. 6,840,426, issued January 11, 2005, and hereby agrees that any patent issued on the above-identified application shall be enforceable only for and during such time as the said U.S. Patent No. 6,840,426 and the above-identified application are commonly owned.

Petitioner, however, does not disclaim the terminal part of any patent granted on the instant application prior to the expiration date of the full statutory term, defined in 35 USC 154 to 156 and 173, of the above-listed U.S. Patent No. 6,840,426 in the event that U.S. Patent No. 6,840,426 expires: for failure to pay a maintenance fee; is held

unenforceable; is found invalid; is statutorily disclaimed in whole or terminally disclaimed under 37 CFR 1.321; has all claims cancelled by a reexamination certificate; is reissued; or is otherwise terminated prior to expiration of the above-referred-to full statutory term, except for the separation of legal title as stated above.

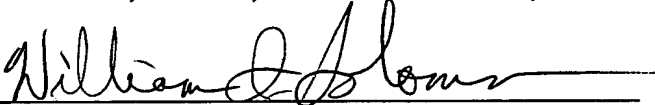
This disclaimer is to be binding with respect to any patent granted on the above-identified application, and is binding upon grantees, their successors, or assignees of any interests.

The undersigned is an attorney of record in this application and is empowered to act on behalf of Hitachi Chemical Co., Ltd. for execution and submission of Terminal Disclaimers, in accordance with the provisions of 37 CFR 1.321(b) and (c), effective January 4, 1994.

The undersigned hereby declares that all statement made herein of his knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine, or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Respectfully submitted,

**ANTONELLI, TERRY, STOUT & KRAUS, LLP**

By   
William I. Solomon  
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Attachment: Copy of Assignment (1 pg.)

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# ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## PANEL STRUCTURE, A FRICTION WELDING METHOD, AND A PANEL

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures :

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)	Witnesses (立会人サイン)
1) <u>Kinya Aota</u>	<u>21, February, 1997</u>	<u>Toshiaki Sagawa</u>
2) <u>Tsuyoshi Takenaka</u>	<u>21, February, 1997</u>	<u>Toshiaki Sagawa</u>
3) <u>Yasuo Ishimaru</u>	<u>21 - February, 1997</u>	<u>Toshiaki Sagawa</u>
4) _____	_____	_____
5) _____	_____	_____
6) _____	_____	_____
7) _____	_____	_____
8) _____	_____	_____
9) _____	_____	_____
10) _____	_____	_____